

Integration Of Semiconductor Membranes With Piezoelectric Substrates

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Inventors: Max Lagally, Abhishek Bhat, Frank Flack, Shelley Scott, Robert Blick

The Invention

Piezoelectrically actuated devices constructed from thin semiconductor membranes bonded directly to piezoelectric substrates are provided. Methods for fabricating these devices are also provided. The bonding of the semiconductor to the piezoelectric material does not require the use of any intermediate layers, such as bonding agents.

Additional Information

For More Information About the Inventors

Max Lagally

Tech Fields

<u>Semiconductors & Integrated Circuits : Design & fabrication</u>

For current licensing status, please contact Jeanine Burmania at jeanine@warf.org or 608-960-9846

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